



Data Sheet

July 1999 File Number 1514.3

8A, 200V, 0.600 Ohm, Logic Level, N-Channel Power MOSFET

This N-Channel enhancement mode silicon gate power field effect transistor is specifically designed for use with logic level (5V) driving sources in applications such as programmable controllers, automotive switching and solenoid drivers. This performance is accomplished through a special gate oxide design which provides full rated conduction at gate biases in the 3V to 5V range, thereby facilitating true on-off power control directly from logic circuit supply voltages.

Formerly developmental type TA09534.

Ordering Information

PART NUMBER	PACKAGE	BRAND
RFP8N20L	TO-220AB	RFP8N20L

NOTE: When ordering, include the entire part number.

Features

- 8A, 200V
- r_{DS(ON)} = 0.600Ω
- Design Optimized for 5V Gate Drives
- Can be Driven Directly from QMOS, NMOS, TTL Circuits
- · Compatible with Automotive Drive Requirements
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- · Linear Transfer Characteristics
- High Input Impedence
- · Majority Carrier Device
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging

JEDEC TO-220AB



Absolute Maximum Ratings $T_{C} = 25^{\circ}C$, Unless Otherwise Specified

	RFP8N20L	UNITS
Drain to Source Voltage (Note 1)V _{DS}	200	V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	200	V
Continuous Drain CurrentI _D	8	А
Pulsed Drain Current (Note 3)	20	А
Gate to Source Voltage	10	V
Maximum Power Dissipation	60	W
Above T _C = 25 ^o C, Derate Linearly	0.48	W/oC
Operating and Storage Temperature	-55 to 150	°C
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10sT _L Package Body for 10s, See Techbrief 334T _{pkg}	300 260	°C 2°

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}C$ to $125^{\circ}C$.

Electrical Specifications $T_{C} = 25^{\circ}$	C, Unless Otherv	vise Specified					
PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	$I_{D} = 250 \mu A, V_{GS} = 0$		200	-	-	V
Gate to Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250 \mu A$		1	-	2	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 0.8 x Rated BV _{DSS}	T _C = 25 ^o C	-	-	1	μΑ
		V _{DS} = 0.8 x Rated BV _{DSS}	T _C = 125 ^o C	-	-	50	μA
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = 10V, V_{DS} = 0$		-	-	100	nA
Drain to Source On-Voltage (Note 2)	V _{DS(ON)}	I _D = 8A, V _{GS} = 5V		-	-	4.8	V
Drain to Source On Resistance (Note 2)	rDS(ON)	$I_D = 4A, V_{GS} = 5V$		-	-	0.600	Ω
Turn On Delay Time	t _{d(ON)}	$I_D = 4A, V_{DD} = 50V, R_G = 6.25, V_{GS} = 5V$		-	15	45	ns
Rise Time	t _r			-	45	150	ns
Turn Off Delay Time	t _{d(OFF)}			-	100	135	ns
Fall Time	t _f			-	60	105	ns
Input Capacitance	C _{ISS}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz		-	-	900	pF
Output Capacitance	C _{OSS}			-	-	250	pF
Reverse Transfer Capacitance	C _{RSS}			-	-	120	pF
Thermal Resistance Junction to Case	R _{θJC}	RFP8N20L				2.083	°C/W

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	ТҮР	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V _{SD}	I _{SD} = 4A	-	-	1.4	V
Diode Reverse Recovery Time	t _{rr}	$I_{SD} = 4A$, $dI_{SD}/dt = 100A/\mu s$	-	250	-	ns

NOTES:

2. Pulsed: pulse duration = $300\mu s$ max, duty cycle = 2%.

3. Repetitive rating: pulse width limited by maximum junction temperature.

Typical Performance Curves Unless Otherwise Specified







FIGURE 3. SATURATION CHARACTERISTICS







FIGURE 2. FORWARD BIAS SAFE OPERATING AREA



FIGURE 4. TRANSFER CHARACTERISTICS





Typical Performance Curves Unless Otherwise Specified (Continued)











NOTE: Refer to Intersil Application Notes AN7254 and AN7260. FIGURE 9. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms



FIGURE 10. SWITCHING TIME TEST CIRCUIT



FIGURE 11. RESISTIVE SWITCHING WAVEFORMS

Test Circuits and Waveforms (Continued)



FIGURE 12. GATE CHARGE TEST CIRCUIT



FIGURE 13. GATE CHARGE WAVEFORMS

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